



AT-12815/1  
PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Mostafazadeh et al.

Attorney Docket No.:  
NSC1P217D2/NS-3877-2

Application No.: 09/625,071

Examiner: Clark, S.

Filed: July 25, 2000

Group: 2815

Title: LEAD FRAME CHIP SCALE PACKAGE

TECHNOLOGY CENTER 2306

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**CERTIFICATE OF MAILING**

I hereby certify that this correspondence is being deposited with the United States Postal Service as First Class Mail to: Commissioner for Patents, Washington, DC 20231 on August 27, 2001.

Signed: Lara M. Nelson

Lara M. Nelson

**AMENDMENT TRANSMITTAL**

Commissioner for Patents  
Washington, DC 20231

Sir:

Transmitted herewith is an Amendment in the above-identified application.

The fee has been calculated as shown below.

	Claims After Amendment		Highest Previously Paid For	Present Extra	Small Entity Rate Fee	Large Entity Rate Fee
Total Claims	07	MINUS	20	00	x 9 =	x 18 =
Independent Claims	01	MINUS	03	00	x 40 =	x 80 =
Multiple Dependent Claim Present and Fee Not Previously Paid					\$135.00	\$270.00
Total					\$	\$

- ☒ Applicant(s) hereby petition for a 01 month extension(s) of time to respond to the aforementioned Office Action.
- ☒ Applicant(s) believe that no (additional) Extension of Time is required; however, if it is determined that such an extension is required, Applicant(s) hereby petition that such an extension be granted and authorize the Commissioner to charge the required fees for an Extension of Time under 37 CFR 1.136 to Deposit Account No. 500388.
- ☒ Enclosed is our Check No. 12168 in the amount of \$110.00 to cover the additional claim fee and/or extension of time fees.
- ☒ Please charge the required fees, or any additional fees required to facilitate filing the enclosed response, to Deposit Account No. 500388 (Order No. NSC1P217D2).

08/30/2001 SDENB0B1 00000017 09625071

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110.00 0P

Respectfully submitted,  
BEYER WEAVER & THOMAS, LLP

Steve D Beyer  
Steve D Beyer  
Reg. No. 31,234

P.O. Box 778  
Berkeley, CA 94704-0778



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(AEE)  
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9-5-01  
T. Flores

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Signed:

*Lara M. Nelson*  
Lara M. Nelson

**RESPONSE TO FINAL OFFICE ACTION**

Commissioner for Patents  
Washington, DC 20231

Dear Sir:

In response to the final office action dated May 22, 2001, please enter the following amendments and remarks.

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**IN THE CLAIMS**

Please replace the existing claim set with the following revised claim set. A marked up version of the claims illustrating the changes made is provided as an Appendix to this response.

11. (Twice Amended)

A lead frame panel suitable for forming an array of integrated circuit packages for accommodating a semiconductor die, the lead frame panel having an array of device areas, each device area being suitable for forming an independent integrated circuit package and comprising: